

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20190327001.0 Notification of the addition of a Topside Inductor Coating on select devices Information Only

Date: March 28, 2019 **To:** Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN www admin team@list.ti.com). For sample requests or sample related questions, contact the TI Samples Team at pcn sr team@list.ti.com.

Sincerely,

PCN Team SC Business Services

20190327001.0 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPSM84424MOLR	null
TPSM84624MOLR	null
TPSM846C23MOLR	null
TPSM846C24MOLR	null
TPSM84824MOLR	null

Technical details of this Product Change follow on the next page(s).

PCN I	CN Number: 20190327001.0				PC	N Date:	Mar 28 2019		
Title: Notification of the addition of a Topside Inductor Coating on select devices							devices		
Customer Contact: PCN Manager			Dept:	Quality Services					
Change Type:									
	Assembly Site		Assembly Process				Assembly Materials		
	Design		Datasheet				Mechanical Specification		
	est Site	\boxtimes	Packing/Shipping/Labeling				Test Process		
V	Vafer Bump Site		Wafer Bump Material			Wafer Bump Process			
V	Vafer Fab Site		Wafer I	Wafer Fab Materials		Wafer Fab Process		b Process	
			Part nu	mber ch	ange				

PCN Details

Description of Change:

This letter is to inform customers an improvement to the assembly process of the devices in the product affected section below. These devices will now be subject to a topside inductor coating step which will improve the marking legibility. See below.

What No Coating Topside Inductor Coating

Example Picture #1

Example Picture #2

Example Picture #2

APQC G4

TPSM846C24

APQC G4

Reason for Change:

To improve AVI performance

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
N/a					
Product Affected:					
TPSM84424MOLR	TPSM846C23MOLR	TPSM846C24MOLR	TPSM84824MOLR		
TPSM84624MOLR					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com